

TEXT SEARCH

APPLICATION # 10644,487

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S22	113053	((board or substrate) with (insulation adj film or resist or mask)).ab,ti,clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/24 18:02
S23	5854	((board or substrate) with (insulation adj film or resist or mask) with (thickness)).ab,ti,clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/24 18:03
S24	301	S23 and (opening adj portion or exposed adj portion)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/24 18:04
S25	214	S23 and (recess)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/24 18:04
S26	30	S24 and S25	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/24 18:06
S27	485	S24 or S25	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/24 18:05
S28	448	S27 not (S26 or S20 or S13 or S17 or S15 or S12)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/24 18:14
S29	149	((wiring) with (electrode\$1) with (resist or solder adj mask or insulating adj film) with (thickness)).ab.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/24 18:14

S30	146	S29 not (S27 or S26 or S20 or S13 or S17 or S15 or S12)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/24 18:19
S33	60567	"174"/\$.ccls.	US-PGPUB; USPAT	OR	OFF	2005/03/29 11:17
S34	85816	"361"/\$.ccls.	US-PGPUB; USPAT	OR	OFF	2005/03/29 11:17
S35	167962	"257"/\$.ccls.	US-PGPUB; USPAT	OR	OFF	2005/03/29 11:18
S36	128224	"29"/\$.ccls.	US-PGPUB; USPAT	OR	OFF	2005/03/29 11:19
S37	406048	S33 or S34 or S35 or S36	US-PGPUB; USPAT	OR	OFF	2005/03/29 11:20
S38	57356	S37 and (resist or solder adj mask or insulating adj film)	US-PGPUB; USPAT	OR	OFF	2005/03/29 11:23
S39	170048	S37 and (opening or exposed or exposing)	US-PGPUB; USPAT	OR	OFF	2005/03/29 11:21
S40	142942	S37 and (electrode\$1 or land\$1 or pad\$1)	US-PGPUB; USPAT	OR	OFF	2005/03/29 11:22
S41	33879	S38 and S39 and S40	US-PGPUB; USPAT	OR	OFF	2005/03/29 11:22
S42	12209	S41 and ((resist or solder adj mask or insulating adj film) with (thick or thickness))	US-PGPUB; USPAT	OR	OFF	2005/03/29 11:26
S43	44	S42 and straddle\$2	US-PGPUB; USPAT	OR	OFF	2005/03/29 11:26
S55	10	(mounting adj board or pwb or pcb or wiring adj board or circuit adj board) with (resit or mask or protection adj layer or protective adj layer or protective adj film) with (width) with (thick or thickness)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/29 18:28
S56	431	(mounting adj board or pwb or pcb or wiring adj board or circuit adj board) with (resit or mask or protection adj layer or protective adj layer or protective adj film) with (thick or thickness)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/29 18:40